Attorney's Docket No.: 111079-134718 Page 1 of 5
First Named Inventor: Chuan Hu Application No.: Not Yet Assigned
Title: BUMPLESS DIE AND HEAT SPREADER LID MODULE BONDED TO BUMPED DIE

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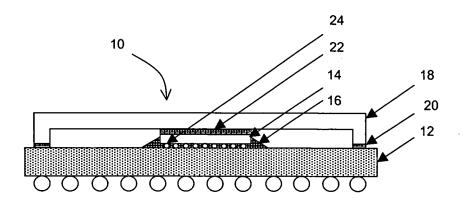


FIG. 1 (PRIOR ART)

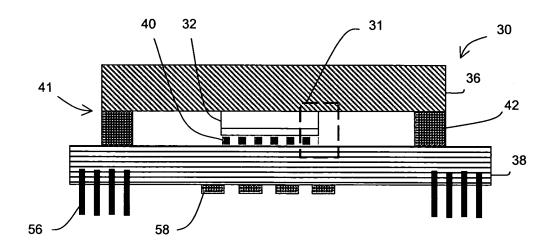


FIG. 2

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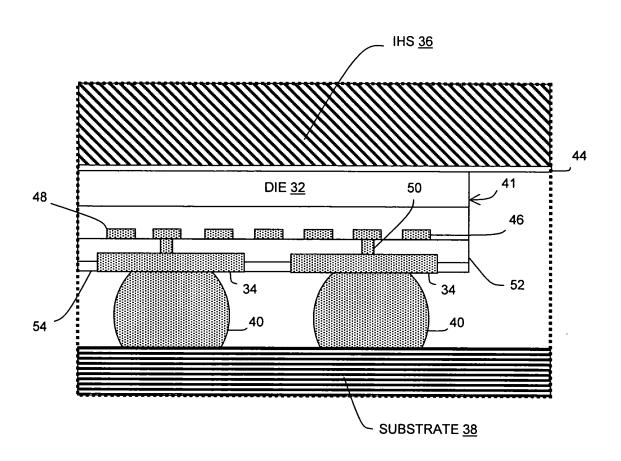
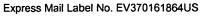


FIG. 3



60 66 **FABRICATE TRANSISTORS &** INTERCONNECT STRUCTURES AND PASSIVATION

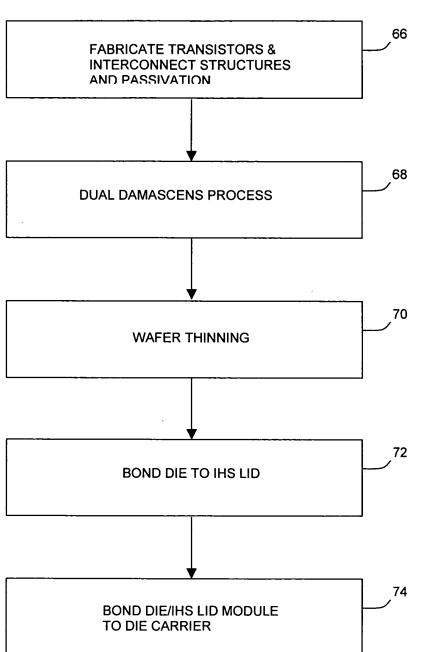


FIG. 4

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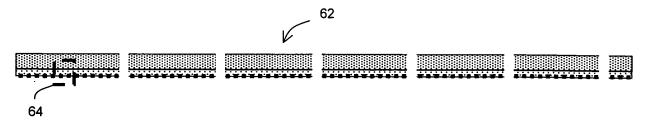


FIG. 5

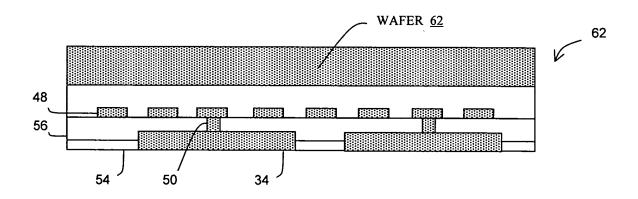


FIG. 6

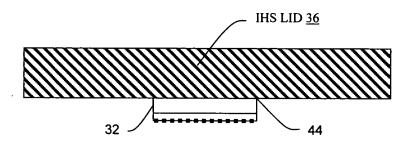


FIG. 7

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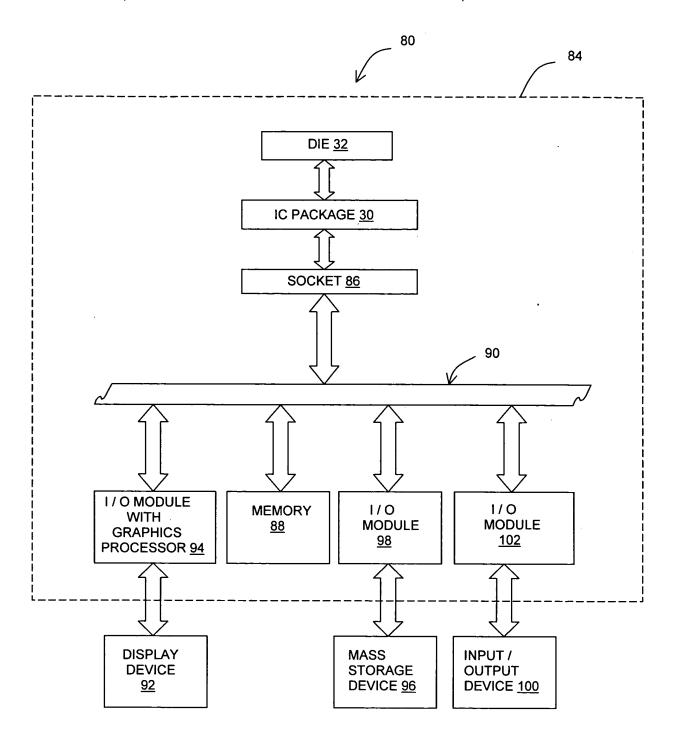


FIG. 8